EB3250A Series



REGULATORY COMPLIANCE

Lead Free	EU RoHS	China RoHS	REACH
\bigotimes	2011/65 + 2015/863	Ð	SVHC
COMPLIANT	COMPLIANT	COMPLIANT	COMPLIANT



ITEM DESCRIPTION

Automotive Grade Quartz Crystal Resonator 3.2mm x 5.0mm x 1.1mm 2 Pad Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICATIONS				
Nominal Frequency	7.6MHz to 54MHz			
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over -40°C to +85°C ±30ppm at 25°C, ±50ppm over -40°C to +85°C ±15ppm at 25°C, ±30ppm over -40°C to +85°C ±15ppm at 25°C, ±20ppm over -40°C to +85°C ±10ppm at 25°C, ±20ppm over -40°C to +85°C ±50ppm at 25°C, ±100ppm over -40°C to +105°C ±30ppm at 25°C, ±50ppm over -40°C to +125°C ±30ppm at 25°C, ±50ppm over -40°C to +125°C			
Aging at 25°C	±3ppm/year Maximum			
Load Capacitance	Series Resonant, 8pF Parallel Resonant to 32pF Parallel Resonant			
Shunt Capacitance	5pF Maximum			
Equivalent Series Resistance	100 Ohms Maximum over Nominal Frequency of 7.6MHz to 11.999999MHz 60 Ohms Maximum over Nominal Frequency of 12MHz to 13.999999MHz 50 Ohms Maximum over Nominal Frequency of 14MHz to 19.999999MHz 40 Ohms Maximum over Nominal Frequency of 20MHz to 54MHz			
Mode of Operation	AT-Cut Fundamental			
Drive Level	300µWatts Maximum			
Crystal Cut	AT-Cut			
Spurious Response	Measured from Fo to Fo +5000ppm -3dB Minimum			
Storage Temperature Range	-50°C to +150°C			
Insulation Resistance	Measured at 100Vdc 500 Megaohms Minimum			

EB3250A Series



PART NUMBERING GUIDE

Series

Automotive Quartz Crystal Resonator 3.2mm x 5.0mm x 1.1mm 2 Pad Ceramic Surface Mount (SMD)

Frequency Tolerance/Stability-

- $C = \pm 50$ ppm at 25°C, ± 100 ppm over -40°C to +85°C F = ± 30 ppm at 25°C, ± 50 ppm over -40°C to +85°C J = ± 15 ppm at 25°C, ± 30 ppm over -40°C to +85°C
- $\begin{array}{l} J = \pm 15 ppm \mbox{ at } 25^{\circ} C, \pm 30 ppm \mbox{ over } -40^{\circ} C \mbox{ to } \pm 85^{\circ} C \\ M = \pm 15 ppm \mbox{ at } 25^{\circ} C, \pm 20 ppm \mbox{ over } -40^{\circ} C \mbox{ to } \pm 85^{\circ} C \\ Q = \pm 10 ppm \mbox{ at } 25^{\circ} C, \pm 20 ppm \mbox{ over } -40^{\circ} C \mbox{ to } \pm 85^{\circ} C \\ U = \pm 50 ppm \mbox{ at } 25^{\circ} C, \pm 100 ppm \mbox{ over } -40^{\circ} C \mbox{ to } \pm 105^{\circ} C \\ V = \pm 30 ppm \mbox{ at } 25^{\circ} C, \pm 100 ppm \mbox{ over } -40^{\circ} C \mbox{ to } \pm 105^{\circ} C \\ X = \pm 50 ppm \mbox{ at } 25^{\circ} C, \pm 100 ppm \mbox{ over } -40^{\circ} C \mbox{ to } \pm 125^{\circ} C \\ Y = \pm 30 ppm \mbox{ at } 25^{\circ} C, \pm 50 ppm \mbox{ over } -40^{\circ} C \mbox{ to } \pm 125^{\circ} C \\ \end{array}$

EB3250A X A 20 -27.000M TR Packaging Options Blank = Bulk (Cut Tape) TR = Tape & Reel

Nominal Frequency

Load Capacitance

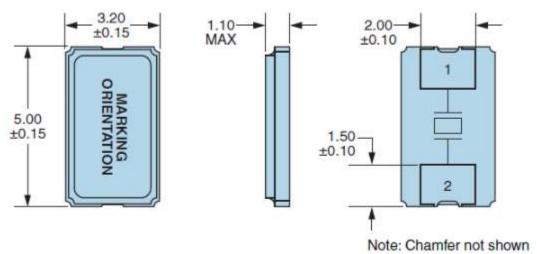
S = Series Resonant XX = 8pF Parallel Resonant to 32pF Parallel Resonant

Mode of Operation

A = AT-Cut Fundamental

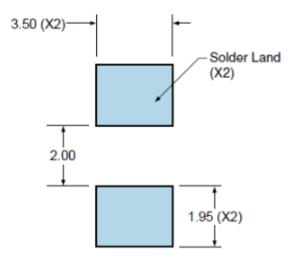


MECHANICAL DIMENSIONS



Seam Sealed Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm)

SUGGESTED SOLDER PAD LAYOUT



PIN	CONNECTION
1	Crystal
2	Crystal

All Tolerances are ±0.1

All Dimensions in Millimeters

EB3250A Series

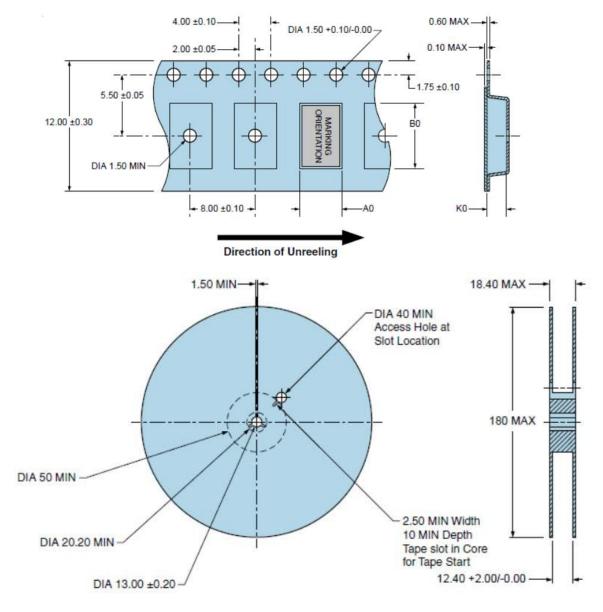


TAPE & REEL DIMENSIONS

Quantity per Reel: 1,000 Units

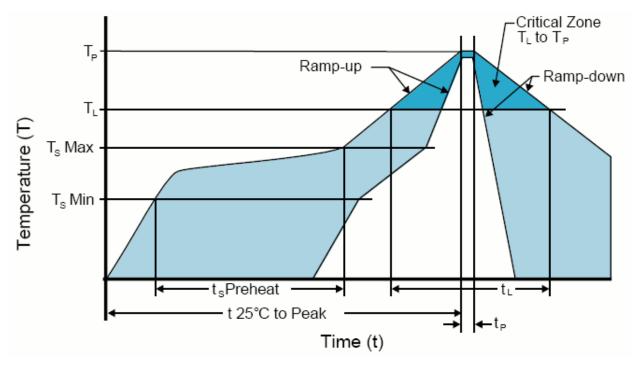
All Dimensions in Millimeters

Compliant to EIA-481





RECOMMENDED SOLDER REFLOW METHOD



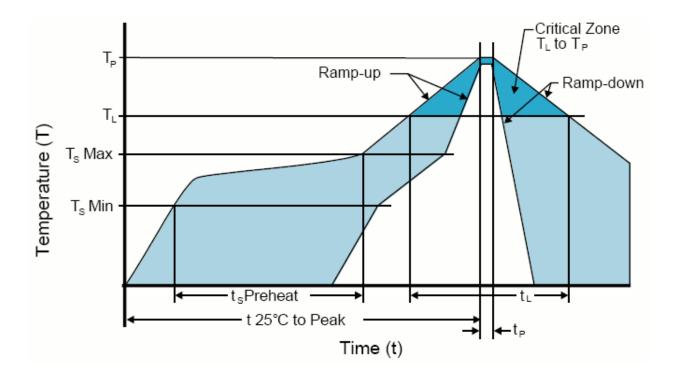
HIGH TEMPERATURE INFRARED/CONVECTION			
T_s MAX to T_L (Ramp-up Rate)	3°C/Second Maximum		
Preheat			
- Temperature Minimum (Ts MIN)	150°C		
- Temperature Typical (T _s TYP)	175°C		
	200°C		
- Time (t _s MIN)	60 - 180 Seconds		
Ramp-up Rate (T _L to T _P)	3°C/Second Maximum		
Time Maintained Above:			
- Temperature (T∟)	217°C		
- Time (t∟)	60 - 150 Seconds		
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum		
Target Peak Temperature(T _P Target)	250°C +0/-5°C		
Time within 5°C of actual peak (t _p)	20 - 40 Seconds		
Ramp-down Rate	6°C/Second Maximum		
Time 25°C to Peak Temperature (t)	8 Minutes Maximum		
Moisture Sensitivity Level	Level 1		
Additional Notes	Temperatures shown are applied to body of device.		

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION			
T_s MAX to T_L (Ramp-up Rate)	5°C/Second Maximum		
Preheat			
- Temperature Minimum (Ts MIN)	N/A		
 Temperature Typical (T_s TYP) 	150°C		
- Temperature Maximum(T _s MAX)			
- Time (t _s MIN)	30 - 60 Seconds		
Ramp-up Rate (T _L to T _P)	5°C/Second Maximum		
Time Maintained Above:			
- Temperature (T _L)	150°C		
- Time (t∟)	200 Seconds Maximum		
Peak Temperature (T _P)	245°C Maximum		
Target Peak Temperature(T _P Target)	245°C Maximum 2 Times/230°C Maximum 1Time		
Time within 5°C of actual peak (t _P)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time		
Ramp-down Rate	5°C/Second Maximum		
Time 25°C to Peak Temperature (t)	N/A		
Moisture Sensitivity Level	Level 1		
Additional Notes	Temperatures shown are applied to body of device.		

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)